



Title of Change:	EMC change from Samsung ST-7100KS to KHG400 for TO-126 package in SHEDCL.	
Proposed First Ship date:	01 Jan 2021 or earlier if approved by customer	
Contact Information:	Contact your local ON Semiconductor Sales Office or Khairil.FK@onsemi.com	
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or PCN.samples@onsemi.com Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Lalan.Ortega@onsemi.com	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com	
Marking of Parts/ Traceability of Change:	Affected products will be identified by date code	
Change Category:	Assembly Change	
Change Sub-Category(s):	Material Change	
Sites Affected:		
ON Semiconductor Sites	External Foundry/Subcon Sites	
None	SHANTOU HUASHAN Electronic Devices Co., Ltd., China	
Description and Purpose:		
<p>ON Semiconductor wishes to inform our customers of a change in mold compounds used for the devices listed in this PCN.</p> <p>This is the final product change notification (FPCN) of IPCN22647.</p> <p>This change is a result of an End of Life notification received from Samsung for several of their SDI Mold Compounds.</p> <p>Due to the discontinuance of the SDI mold compounds, ON Semiconductor will only have limited supplies of the existing material and in some cases this may not allow for the normal change notification period.</p> <p>All other aspects of the impacted products (form, fit, function) will remain unchanged.</p>		
	Before Change Description	After Change Description
Mold Compound	ST7100KS	KHG400

**Reliability Data Summary:**

QV DEVICE NAME: MJE340STU (PTI : FD)

RMS : V67650, O69434

PACKAGE : TO126 3L AU SNGL PBF

Test	Specification	Condition	Interval	Results
EV	JEDS22 B101	External Visual, Device construction, marking, and workmanship		0/231
HTRB	JESD22-A108	Ta = 150°C, 80% rated V	1008 hrs	0/231
HTSL	JESD22-A103	Ta = 150°C	1008 hrs	0/231
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta = +25°C, delta Tj=100°C On/off = 2.0 min	15000 cyc	0/231
TC	JESD22-A104	Ta = -55°C to +150°C	1000 cyc	0/231
AC	JESD22-A102	121°C, 100% RH, 15.5psig, unbiased	96 hrs	0/231
H3TRB	JESD22 A101	Ta = 85°C, 85% RH, V=80% rated V	1008 hrs	0/231
RSH	JESD22- B106	Ta = 265°C, 10 sec		0/90
SD	JSTD002	Ta = 245°C, 10 sec		0/45
PD	JESD22 B100	Per POD / Case Outline, Verify physical dimensions to specifications	0 hr	0/30
SAT	J-STD-035		0 hr	0/75
DPA	AEC Q101-004 Section 4	Following TC	1008 hrs	0/6
DPA	AEC Q101-004 Section 4	Following HTRB	1008 hrs	0/6
DPA	AEC Q101-004 Section 4	Following H3TRB	1008 hrs	0/6
ED	Electrical Distribution / Characterization	Tri Temperature, Per 48A	0 hr	0/30
TR	JESD-24-3, 24-4, 24-6 as appropriate	per device specification, pre & post process change	0 hr	0/10

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
BD13510STU	MJE340STU
BD13516S	MJE340STU
BD13516STU	MJE340STU
BD13710STU	MJE340STU
BD13716S	MJE340STU
BD13716STU	MJE340STU
BD13910S	MJE340STU



BD13910STU	MJE340STU
BD13916S	MJE340STU
BD13916STU	MJE340STU
MJE180STU	MJE340STU
KSD882YS	MJE340STU
KSD882YSTU	MJE340STU
KSC3503DS	MJE340STU
KSC3503DSTU	MJE340STU
KSD1691GSTU	MJE340STU
KSD1691YS	MJE340STU
KSD1691YSTU	MJE340STU
BD679AS	MJE340STU
KSC2690AYS	MJE340STU
KSC2690AYSTU	MJE340STU

Japanese translation of the notification starts here.
通知の日本語訳はここから始まります。

Note: The Japanese version is for reference only. In case of any differences between the English and Japanese version, the English version shall control.

注：日本語版は参照用です。英語版と日本語版の違いがある場合は、英語版が優先されます。



最終製品 / プロセス変更通知

文書番号# : FPCN22647XBB

発行日: 24 Sep 2020

変更件名:	SHEDCL における TO-126 パッケージの封止樹脂を Samsung ST-7100KS 2 から KHG400 に変更	
初回出荷予定日:	01 Jan 2021 またはお客様からの承認が得られた場合はそれ以前	
連絡先情報:	現地のオン・セミコンダクター営業所または Khairil.FK@onsemi.com にお問い合わせください。	
サンプル:	現地のオン・セミコンダクター営業所または PCN.samples@onsemi.com にお問い合わせください。 サンプルは、この変更の初回通知、初回 PCN の日付から 30 日以内に要求してください。 サンプル納入時は、依頼日、数量、特別梱包材/ラベル条件によって異なります。	
追加の信頼性データ:	お客さまの地域のオン・セミコンダクター営業所または Lalan.Ortega@onsemi.com にお問い合わせください。	
通知種別:	これは、お客様宛の最終製品 / プロセス変更通知 (FPCN) です。FPCN は、変更実施の 90 日前に発行されます。 オン・セミコンダクターは、この通知の送付から 30 日以内に書面による問い合わせがない限り、この変更が承諾されたものとみなします。お問い合わせは PCN.Support@onsemi.com 宛てにお願いします。	
変更部品の識別:	影響を受ける製品は日付コードで識別されます	
変更カテゴリ:	組立の変更	
変更サブカテゴリ:	材料の変更	
影響を受ける拠点:		
オン・セミコンダクター拠点:	外部製造工場 / 下請業者拠点:	
無し	SHANTOU HUASHAN Electronic Devices Co., Ltd., China	
説明および目的:	<p>オンセミコンダクターは、本 PCN に記載された製品に使用されているモールドコンパウンドの変更をお客様にお知らせします。</p> <p>これは、IPC22647の最終製品変更通知 (FPCN) です。</p> <p>この変更は、SDIモールドコンパウンドのいくつかについてSamsungから受けた生産終了の通知によるものです。</p> <p>SDIモールドコンパウンドの廃止によって、オン・セミコンダクターでは既存の材料の供給が限定されるようになるため、場合によっては、このことによって通常の変更通知期間が不可能になる場合があります。</p> <p>対象となる製品の他の特徴(形状、適合性、機能)には変更はありません</p>	
	変更前の表記	変更後の表記
モールド・コンパウンド	ST7100KS	KHG400



信頼性データの要約:

デバイス名: MJE340STU (PTI : FD)

RMS : V67650, O69434

パッケージ: TO126 3L AU SNGL PBF

テスト	仕様	条件	間隔	結果
EV	JEDS22 B101	External Visual, Device construction, marking, and workmanship		0/231
HTRB	JESD22-A108	Ta = 150°C, 80% rated V	1008 hrs	0/231
HTSL	JESD22-A103	Ta = 150°C	1008 hrs	0/231
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta = +25°C, delta Tj=100°C On/off = 2.0 min	15000 cyc	0/231
TC	JESD22-A104	Ta = -55°C to +150°C	1000 cyc	0/231
AC	JESD22-A102	121°C, 100% RH, 15.5psig, unbiased	96 hrs	0/231
H3TRB	JEDS22 A101	Ta = 85°C, 85% RH, V=80% rated V	1008 hrs	0/231
RSH	JESD22- B106	Ta = 265°C, 10 sec		0/90
SD	JSTD002	Ta = 245°C, 10 sec		0/45
PD	JESD22 B100	Per POD / Case Outline, Verify physical dimensions to specifications	0 hr	0/30
SAT	J-STD-035		0 hr	0/75
DPA	AEC Q101-004 Section 4	Following TC	1008 hrs	0/6
DPA	AEC Q101-004 Section 4	Following HTRB	1008 hrs	0/6
DPA	AEC Q101-004 Section 4	Following H3TRB	1008 hrs	0/6
ED	Electrical Distribution / Characterization	Tri Temperature, Per 48A	0 hr	0/30
TR	JESD-24-3, 24-4, 24-6 as appropriate	per device specification, pre & post process change	0 hr	0/10

電気的特性の要約:

電気的特性への影響はありません。

影響を受ける部品の一覧:

注: 部品一覧には標準部品番号 (既製品) のみが記載されています。本 PCN の影響を受けるカスタム部品番号は、PCN メールで提供される顧客個別の付録、または PCN カスタマイズポータルに記載されています。

部品番号	認定試験用ピークル
BD13510STU	MJE340STU
BD13516S	MJE340STU
BD13516STU	MJE340STU
BD13710STU	MJE340STU
BD13716S	MJE340STU
BD13716STU	MJE340STU
BD13910S	MJE340STU
BD13910STU	MJE340STU



BD13916S	MJE340STU
BD13916STU	MJE340STU
MJE180STU	MJE340STU
KSD882YS	MJE340STU
KSD882YSTU	MJE340STU
KSC3503DS	MJE340STU
KSC3503DSTU	MJE340STU
KSD1691GSTU	MJE340STU
KSD1691YS	MJE340STU
KSD1691YSTU	MJE340STU
BD679AS	MJE340STU
KSC2690AYS	MJE340STU
KSC2690AYSTU	MJE340STU



Appendix A: Changed Products

DIKG : DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
BD13510STU		MJE340STU	NA	
BD13516STU		MJE340STU	NA	
BD13710STU		MJE340STU	NA	
BD13716S		MJE340STU	NA	
BD13716STU		MJE340STU	NA	
BD13910S		MJE340STU	NA	
BD13910STU		MJE340STU	NA	
BD13916S		MJE340STU	NA	
BD13916STU		MJE340STU	NA	
MJE180STU		MJE340STU	NA	
KSD882YS		MJE340STU	NA	
KSD882YSTU		MJE340STU	NA	
KSC3503DS		MJE340STU	NA	
KSC3503DSTU		MJE340STU	NA	
KSD1691GSTU		MJE340STU	NA	
KSD1691YS		MJE340STU	NA	
KSD1691YSTU		MJE340STU	NA	
BD679AS		MJE340STU	NA	
KSC2690AYS		MJE340STU	NA	
KSC2690AYSTU		MJE340STU	NA	
BD13516S		MJE340STU	NA	